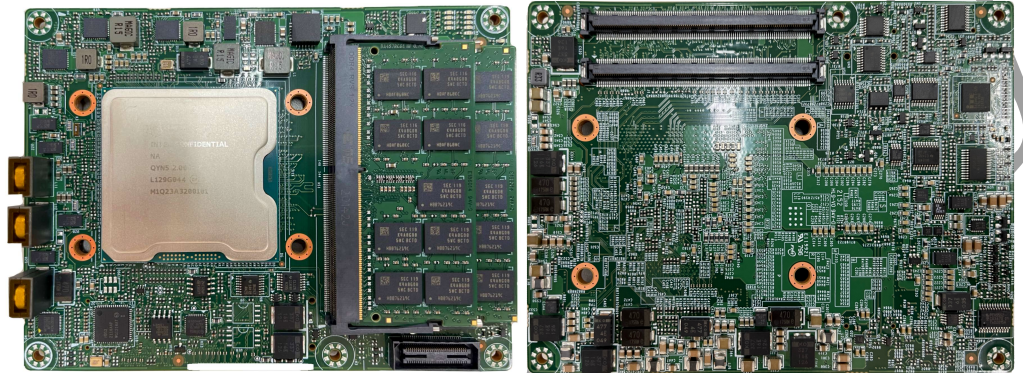


# ICE LAKE COMe CPU Module

## Bare-Metal Hardware

### CPUC-ICX-0321-ZZ



The product is a basic form factor Computer-On-Module (COM) board that is designed to support a wide range of applications primarily in the commercial market segment. It is a Powerful Module in the COM roadmap and is therefore designed to be compatible with the existing System boards as well as FRS customer carrier boards designed to accept other Type 7 basic form factor COM Express module. The COM mezzanine form factor is the “COM Express” standard from PICMG

## Key Features and Benefits

Processor Platform (ICE Lake)

COMe 3.0 spec update

2x DDR4 ECC SO-DIMM

BIOS recovery function Add

Additional I/O support

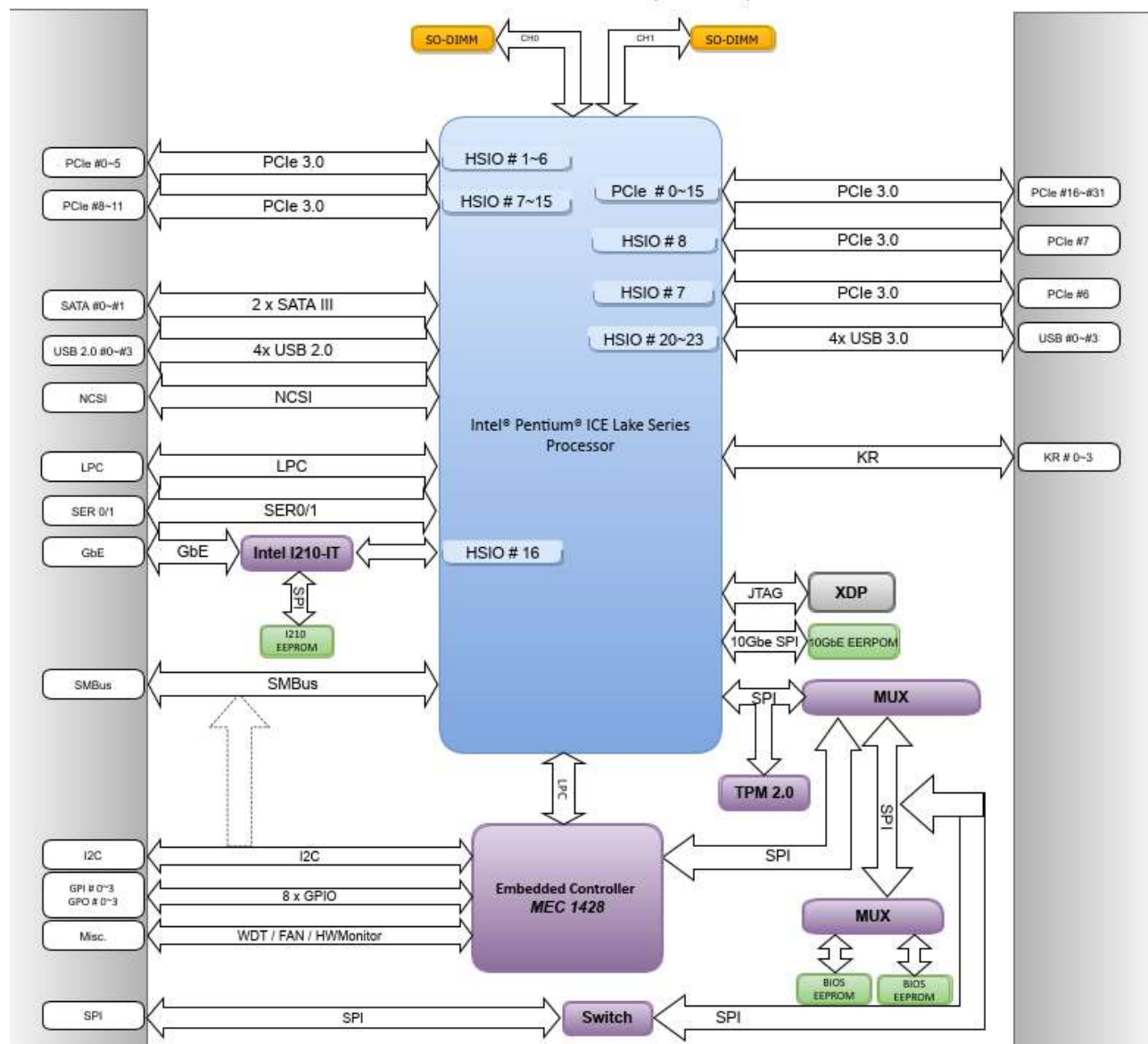
- Up to 32x PCIe lanes
- 1x GbE (MDI), 4x 10GbE (KR)
- USB 4x 2.0, 4x 3.0
- UEFI BIOS

The program consists of one logical module with several different SKUs, one heat spreader, or a passive heat sink. It re-uses the system board.

# ICE Lake series

COM Express® Module 125 x 95 mm    AT / ATX Mode    -40 °C ~ +85 °C  
(Selected SKUs)

DDR4 ECC 2-Channel (base on SKU)



Form Factor	Type 7, Mid COM-Express® ( 125 x 95 mm)	
Processor	Intel® Pentium®	
	D1713NTe	D1734NT
Core	4	8
Freq.	3.3GHz	3.1GHz
Cache	10M	15M
Processor TDP	TBD	
BIOS	AMI BIOS	
In-Band ECC	Yes	
Memory	2 x DIMM up to 64GB	
SATA	2 x SATA III	
USB	4 x USB 3.1, 4 x USB 2.0	
Ethernet	1x GbE (MDI), 4x 10GbE (KR)	
Serial I/O	GPIO	8 x GPIO
	I2C	Baud Rate: 400KHz
	SMBus	Baud Rate: 100KHz
	UART	TBD
PCI Express	2 x PCIe 3.0 x 16	
Security	TPM 2.0, Intel®AES	

Dimension	125 x 95mm
Power DC IN	DC 12V/5V
Storage Temperature	-40°C to 85°C
Operation Temperature	0°C to 40°C(D1734NT) -40°C to 85°C(D1713NTe)
Certification	TBD
OS	TBD